

Title (en)

ELECTROLYTIC HARD GOLD PLATING SOLUTION AND PLATING METHOD USING SAME

Title (de)

ELEKTROLYTISCHE HARTGOLDPLATTIERUNGSLÖSUNG UND PLATTIERUNGSVERFAHREN DAMIT

Title (fr)

SOLUTION DE DORURE DURE ÉLECTROLYTIQUE ET PROCÉDÉ DE PLACAGE QUI UTILISE CELLE-CI

Publication

EP 2511400 A4 20130724 (EN)

Application

EP 10835855 A 20101130

Priority

- JP 2009279409 A 20091209
- JP 2010071304 W 20101130

Abstract (en)

[origin: WO2011070933A1] Disclosed is a plating solution which does not result in pinholes in a metal film even if the metal film is less than 0.1µm thick. Partial plating is performed using an electrolytic hard gold plating solution containing gold cyanide and/or gold cyanide salt, water-soluble cobalt salt or water-soluble nickel salt, conducting salts of organic acids, an aromatic sulfonic acid compound, a combination of one or more items selected from a group consisting of carboxylic acids, oxycarboxylic acids, and the salts thereof, and a nitrogen-containing five-membered heterocyclic compound. Consequently, pinholes are not caused in a metal film even if the metal film is less than 0.1µm thick.

IPC 8 full level

C25D 3/62 (2006.01)

CPC (source: EP KR)

C25D 3/56 (2013.01 - KR); **C25D 3/62** (2013.01 - EP KR)

Citation (search report)

- [IY] EP 1728898 A2 20061206 - ROHM & HAAS ELECT MAT [US]
- [Y] JP 2009007656 A 20090115 - JAPAN PURE CHEMICAL CO LTD
- [Y] US 6814850 B1 20041109 - MANZ UWE [DE], et al
- [A] EP 2103716 A1 20090923 - ROHM & HAAS ELECT MAT [US]
- See references of WO 2011070933A1

Designated contracting state (EPC)

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